

Tool ID: 501
Tool Location: 118

Equipment Information Sheet

E-Beam Lithography Resist Spinners

Manager: Alan R. Bleier
Backup: John Treichler

607-254-4931
607-254-4949

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- Samples spin at high rpm. Always make sure to wear the face shield and spin with the spinner lid closed. The closed lid will contain any samples if the vacuum fails or the sample breaks

USAGE RESTRICTIONS

Please review electron beam lithography training materials, in AFS, at: shares - public - processes_from_cnf_staff - ElectronBeamLithography - TrainingMaterials (accessible on any general use PC or CNF Thin station at CNF)

SCHEDULING/SIGN-UP RESTRICTIONS

- No scheduling for these tools

Minimum Tool Time: 0 minutes

MATERIALS COMPATIBILITY CATEGORY

Tool Category 5: Class A and B Metals and Compounds

Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared-w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- Use only approved ebeam lithography resists and solvents

Last Updated: 01/11/2022